<u>PATENT</u> IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No.:

Herewith

Filed:

Herewith

Inventors:

Hartmut Mahlkow et al

For:

Solution for Etching Copper Surfaces and Method of Depositing Metal on

Copper Surfaces

Atty Doc. No.: 295-05

PRELIMINARY AMENDMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

Please amend the claims as indicated on the claim amendment pages provided herewith.

Please amend the application by adding the abstract, shown on the abstract page provided herewith.

Respectfully submitted,

John F. McNulty Reg. No. 23,028

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